Thermal Foils & Films

FT_TFO_041_T_30

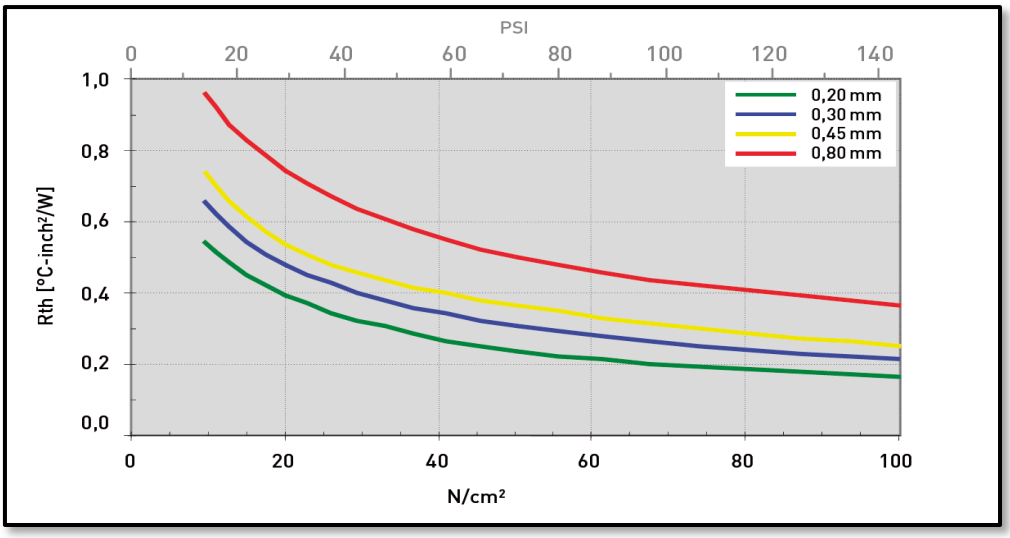
Our Thermal Foams also called Graphic Interfaces are silicone-based thermo-conductive materials that solve the problems of heat dissipation. TFO_041_T is a specially developed heat insulating silicone sheet for applications where low cooling requirements are required. Indeed, it is an excellent thermal conductor of 4.1W/mK, with good thermal resistance facilitating the transfer of heat and does not have electrical insulation. We can cut according to customer plan. All our mattresses are certified UL 94 in V0.

Application Areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED ,Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device,Wireless Hub, DDR Module, etc.

Technical Characteristics

Features	Units	TFO_041_T			
Thickness	mm	0.20	0.30	0.45	0.80
Reinforcement	-	Fiberglass			
Color	-	Gray		White	
Tensile strength	kpsi	3.6	2.9	2.0	1.3
Size	mm	440*510			
Resistance @150 Psi	°C-inch²/W	0.16	0.21	0.24	0.36
Resistance @30 Psi		0.39	0.47	0.53	0.74
Thermal Conductivity	W/mK	4.1			
Temperature	°C	-50 to 200			
Breakdown voltage	kV/AC	3.0	6.5	9.0	> 10
Volume resistance	0hm - cm	1.9×10^{15}	2.4×10^{15}	3.3×10^{15}	4.1×10^{15}
Contante dielectric	@1MHz	3.6			

The TFO_041_T is available in 0.20/0.30/0.45/0.80mm thicknesses.



The results were obtained under laboratory conditions and should be considered only as a guide. As AB2E has no control over its customers' hardware and many other factors, it is the user's responsibility to perform their own tests to ensure that the product meets their needs.